

General purpose PIN diode

BAP51 – 02

FEATURES

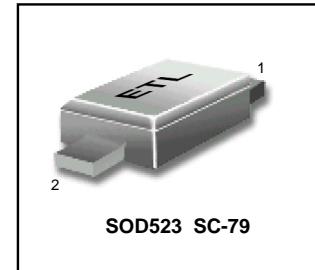
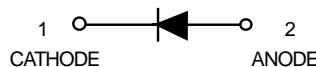
- Low diode capacitance
- Low diode forward resistance.

APPLICATIONS

- General RF applications.

DESCRIPTION

General purpose PIN diode in a SOD523 small SMD plastic package.



LIMITING VALUES In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		–	60	V
I_F	continuous forward current		–	50	mA
P_{tot}	total power dissipation	$T_s = 90^\circ\text{C}$	–	715	mW
T_{sig}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

ELECTRICAL CHARACTERISTICS $T_j = 25^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX.	UNIT
V_F	forward voltage	$I_F = 50 \text{ mA}$	–	0.95	1.1	V
V_R	reverse voltage	$I_R = 10 \text{ mA}$	50	–	–	V
I_R	reverse current	$V_R = 50 \text{ V}$	–	–	100	nA
C_d	diode capacitance	$V_R = 0; f = 1 \text{ MHz}$	–	0.4	–	pF
		$V_R = 1 \text{ V}; f = 1 \text{ MHz}$	–	0.3	0.55	pF
		$V_R = 5 \text{ V}; f = 1 \text{ MHz}$	–	0.2	0.35	pF
r_D	diode forward resistance	$I_F = 0.5 \text{ mA}; f = 100 \text{ MHz}; \text{note 1}$	–	5.5	9	Ω
		$I_F = 1 \text{ mA}; f = 100 \text{ MHz}; \text{note 1}$	–	3.6	6.5	Ω
		$I_F = 10 \text{ mA}; f = 100 \text{ MHz}; \text{note 1}$	–	1.5	2.5	Ω

Note

- Guaranteed on AQL basis: inspection level S4, AQL 1.0.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th,j-s}$	thermal resistance from junction to soldering-point	85	K/W

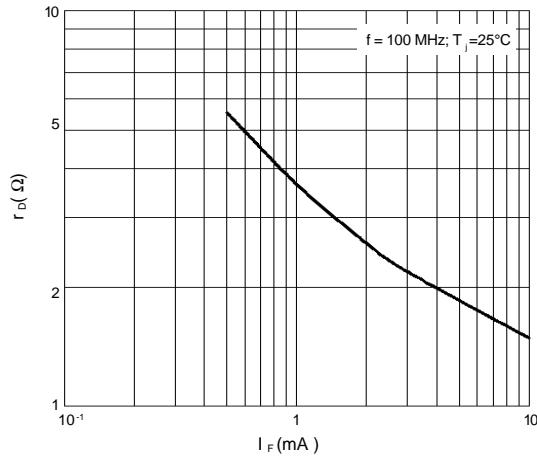


Fig.1 Forward resistance as a function of forward current; typical values.

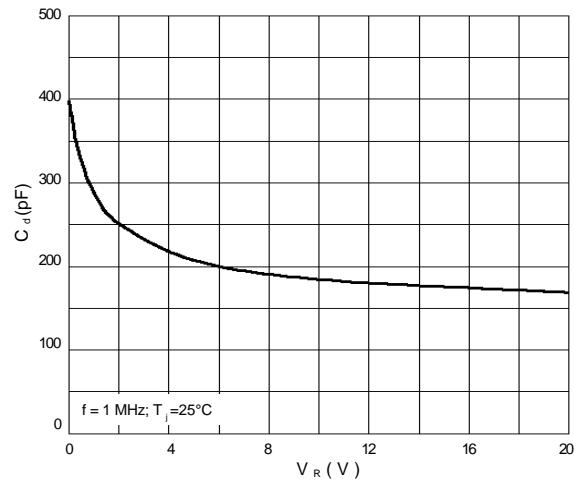


Fig.2 Diode capacitance as a function of reverse voltage; typical values.

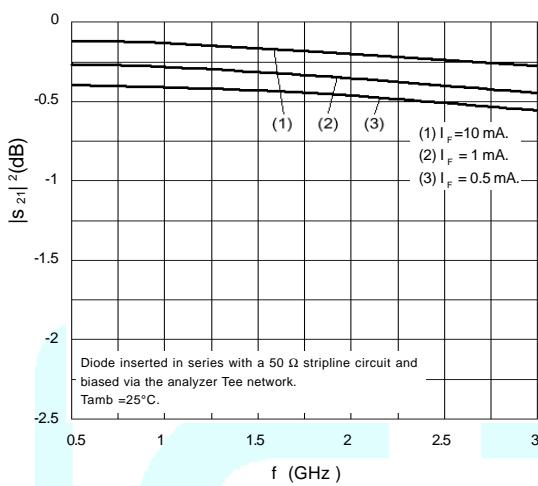


Fig.3 Insertion loss ($|S_{21}|^2$) of the diode in on-state as a function of frequency; typical values.

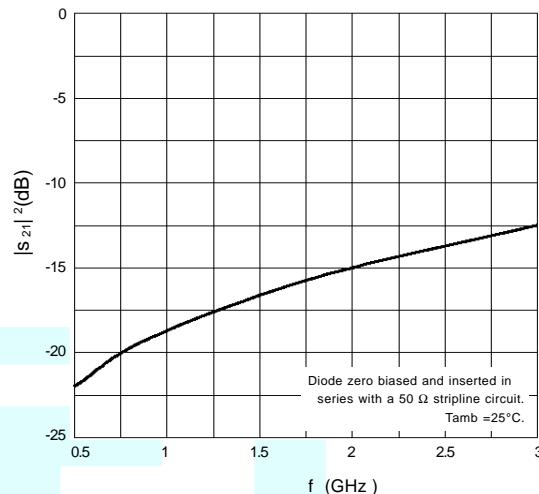


Fig.4 Isolation ($|S_{21}|^2$) of the diode in off-state as a function of frequency; typical values.